

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

| IN RE                         | THE APPLICATION OF  | ) Examiner: Jeremy C. Norris  |
|-------------------------------|---|---|
| Philip 1                      | Andrew Anslow et al.  | ) Group Art Unit: 2827  |
| SERIA                         | L NO.: 0/451,127  | ) Confirmation Number: 8621   |
| FILED                         | : November 30, 1999   | ) Date Allowed: December 24, 2003   |
|                               | High Density Printed Wiring Board Having In-Via Surface Mounting Pads | ) Customer Number: 23644 ) I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450," on March 9, 2004 Name of person signing Jennifer J. Ramirez Signature |
| SUBMISSION OF FORMAL DRAWINGS |   |   |

Honorable Director of Patents and Trademarks P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Submitted herewith are 6 sheets of formal drawings for the above-identified application.

March 8, 2004

Respectfully submitted,

William M. Lee, Jr.

Registration No. 26,935

Barnes & Thornburg

P.O. Box 2786

Chicago, Illinois 60690-2786

(312) 214-4800

(312) 759-5646 (fax)